

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1 – 34 (canceled)

Claim 35 (original): A thermal imaging member comprising

(a) a substrate having first and second opposed surfaces;

(b) first and second image-forming layers carried by said first surface of said substrate, said first image-forming layer being closer to said first surface of said substrate than said second image-forming layer, said first image-forming layer having a lower activation temperature than said second image-forming layer; and

(c) a first interlayer positioned between said first and second image-forming layers.

Claim 36 (original): The thermal imaging member as defined in claim 35 wherein said interlayer comprises an inert material.

Claim 37 (original): The thermal imaging member as defined in claim 35 wherein said interlayer includes a material which undergoes a phase change upon the application of heat thereto.

Claim 38 (original): The thermal imaging member as defined in claim 35 wherein said first and second image-forming layers each has a thickness of from about 0.5 to about 4.0 μm .

Claim 39 (original): The thermal imaging member as defined in claim 35 wherein at least one of said first and second image-forming layers has a thickness of about 2 μm .

Claim 40 (original): The thermal imaging member as defined in claim 35 wherein said first interlayer has a thickness of from about 1 to about 40 μm .

Claim 41 (original): The thermal imaging member as defined in claim 35 wherein said first interlayer has a thickness of from about 14 to about 25 μm .

Claim 42 (original): The thermal imaging member as defined in claim 35 and further including:

(a) a third image-forming layer carried by said first surface of said substrate, said third image-forming layer being farther from said first surface of said substrate than said second image-forming layer and having a higher activation temperature than said second image-forming layer; and

(b) a second interlayer positioned between said second and third image-forming layers.

Claim 43 (original): The thermal imaging member as defined in claim 42 wherein said second interlayer is thinner than said first interlayer.

Claim 44 (original): The thermal imaging member as defined in claim 42 wherein said first image-forming layer has a thickness of from about 0.5 to about 4 μm and comprises a leuco dye and a developer material, each having a melting point of from about 90°C to about 140°C, said second image-forming layer has a thickness of from about 0.5 to about 4 μm and comprises a leuco dye and a developer, each having a melting point of from about 150°C to about 250°C, said third image-forming layer having a thickness of from about 0.5 to about 4 μm and comprising a leuco dye having a melting point of at least 150°C and a developer having a melting point of at least 250°C.

Claim 45 (original): The thermal imaging member as defined in claim 42 wherein said first image-forming layer has a thickness of from about 0.5 to about 4 μm and comprises a leuco dye and a developer material, each having a melting point of from about 90°C to about 140°C, said second image-forming layer has a thickness of from about 0.5 to about 4 μm and comprises a leuco dye and a developer, each having a melting point of from about 150°C to about 250°C, said third image-forming layer having a thickness of from about 0.5 to about 4 μm and comprising a compound which forms color intramolecularly at a temperature of at least 300°C in from about 0.1 to about 2 milliseconds.

Claim 46 (original): The thermal imaging member as defined in claim 35 and further including a topcoat layer and a backcoat layer.

Claim 47 (original): The thermal imaging member as defined in claim 46 and further including

(c) a third image-forming layer carried by said second surface of said substrate.

Claim 48 (original): The thermal imaging member as defined in claim 47 wherein said substrate is transparent and further including a reflective layer adjacent the surface of said third image-forming layer remote from said second surface of said substrate.

Claim 49 (original): The thermal imaging member as defined in claim 35 wherein the thickness of said substrate is less than about 20 μ m.

Claim 50 (original): The thermal imaging member as defined in claim 35 wherein said substrate has a thickness of about 5 μ m.

Claim 51 (original): A thermal imaging member comprising in succession: a first image-forming layer, a first timing layer, a layer of a fixing material, a second timing layer and a second image-forming layer.

Claim 52 (original): The thermal imaging member as defined in claim 51 wherein said first image-forming layer comprises a layer of a first leuco dye in combination with a layer of an acid developer material having a melting point T_7 , said second image-forming layer comprises a layer of a second leuco dye in combination with a layer of an acid developer material having a melting point T_8 , said fixing material has a melting point T_9 and $T_7 < T_8$ and $T_9 < T_7$ and T_8 .

Claim 53 (original): The thermal imaging member as defined in claim 52 wherein said first timing layer is thinner than said second timing layer.

Claim 54 (original): The thermal imaging member as defined in claim 52 and further including a third image-forming layer comprising a layer of a third leuco dye in combination with a layer of an acid developer material having a melting point T_{10} , where $T_{10} > T_7$ and T_8 .

Claim 55 (original): The thermal imaging member as defined in claim 54 wherein said first timing layer is thinner than said second timing layer.

Claim 56 (original): A thermal imaging member comprising in succession: a first layer of a decolorizer material, a first image-forming layer, a first timing layer, a layer of a fixing material, a second timing layer, a second image-forming layer and a second layer of a decolorizer material.